

Electronic Supplementary Information

Mechanical Stabilization of Metallic Microstructures by Insertion of Adhesive Polymer Underlayer for Further Optical and Electrical Application

Tieqiang Wang,^{*a} Guoshuai Song,^a Fuchun Liu,^b Yingqiu Qi,^c Chengsheng Luo,^c
Xuemin Zhang,^a Yunong Li,^a Enhou Han,^b Yu Fu^{*a} and Yonghua Jiao^{*c}

a College of Sciences, Northeastern University, Shenyang 110819, P. R. China, E-mail: wangtieqiang@mail.neu.edu.cn, fuyu@mail.neu.edu.cn;

b State Key Laboratory for Corrosion and Protection, Institute of Metal Research, Chinese Academy of Sciences, Shenyang, 110016, P. R. China;

c College of Life and Health Sciences, Northeastern University, Shenyang 110819, P. R. China, E-mail: jiaoyh@mail.neu.edu.cn.

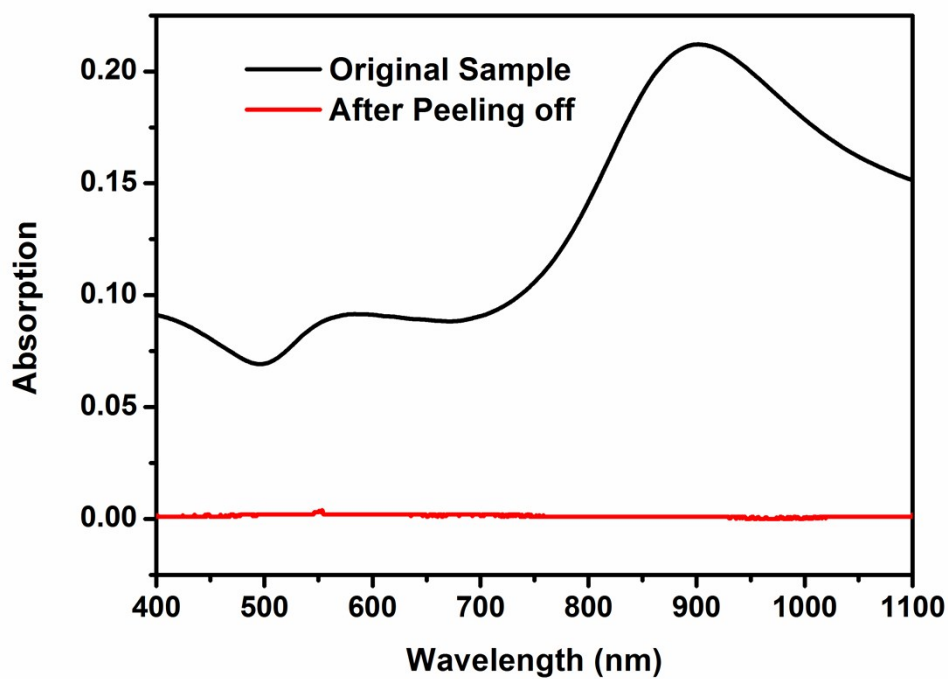


Fig. S1. The absorption spectra of the sample before and after the Au TA was peeled off from the substrate.

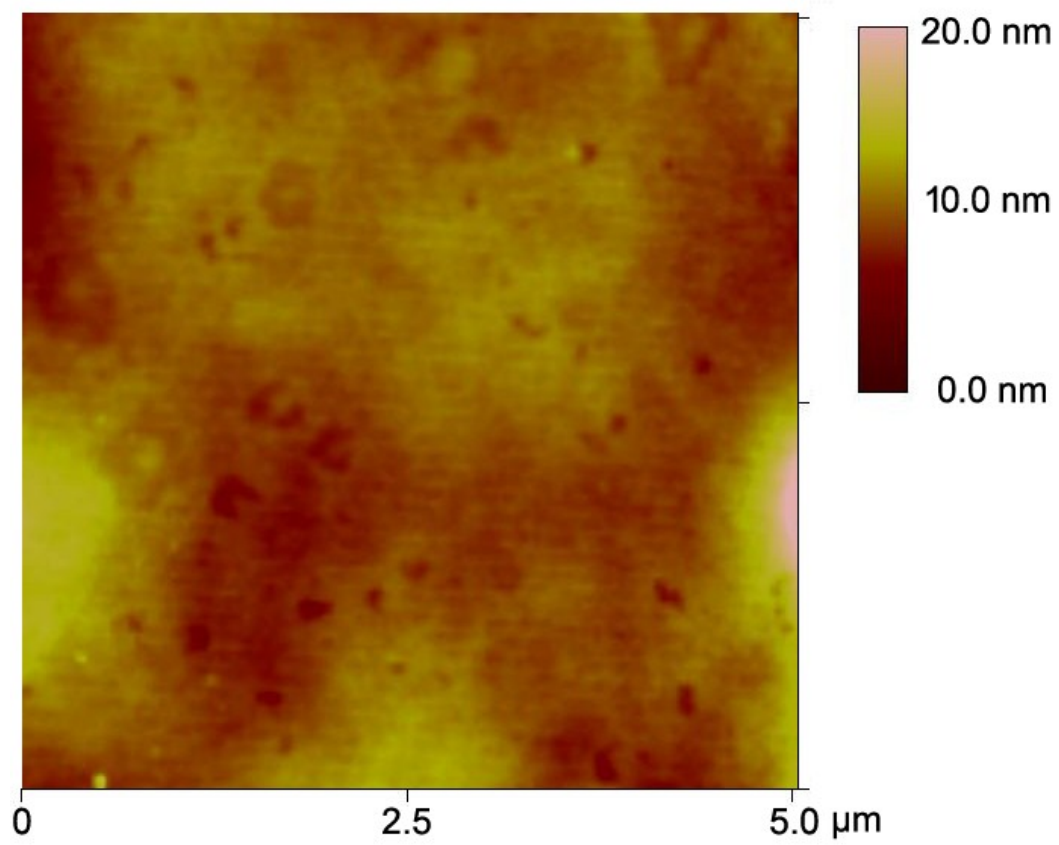


Fig. S2. The AFM image of the PEI/PAA couple layer.

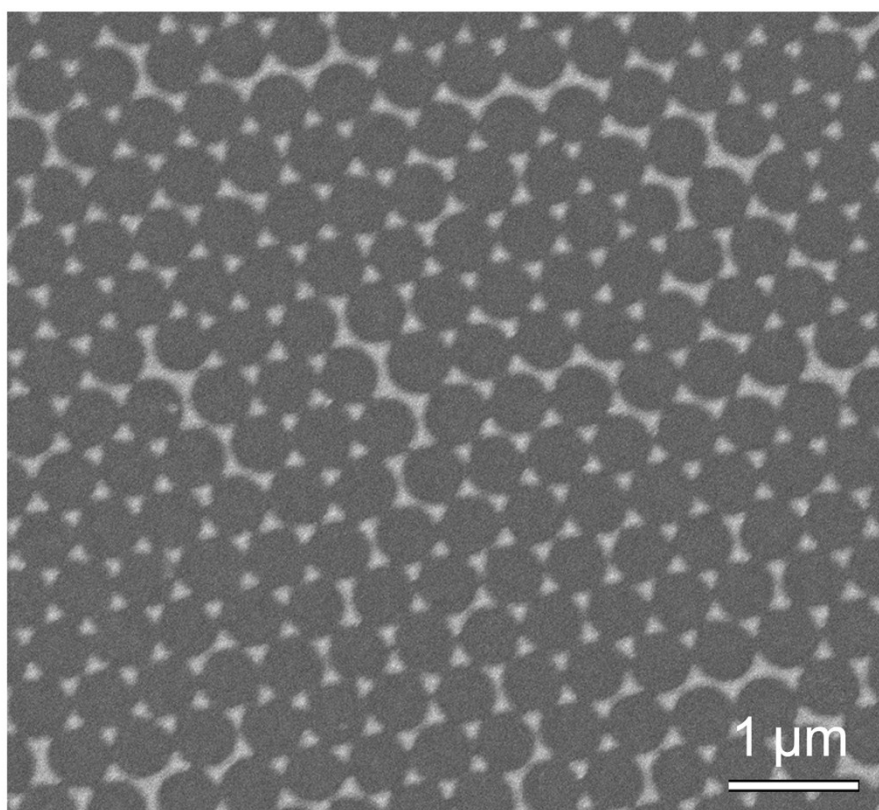


Fig. S3. The SEM images of the as-enhanced Au TA by PAT after multi-time test.

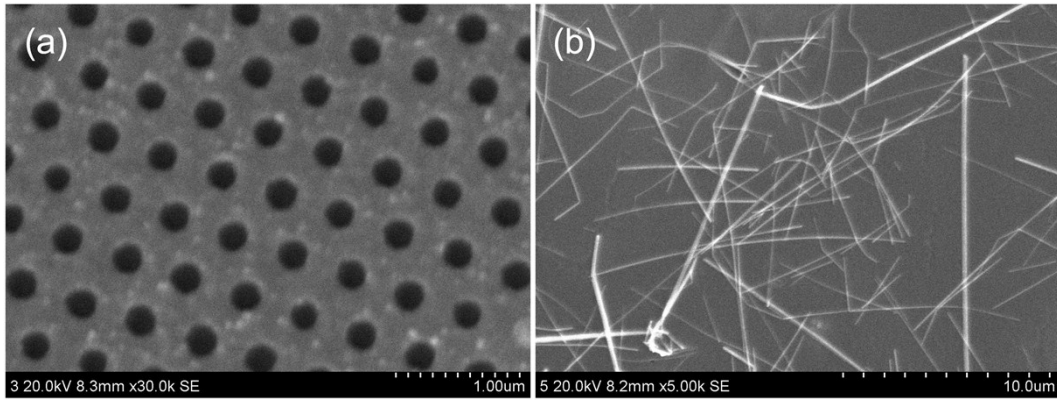


Fig. S4. The SEM images of the as-enhanced Ag nanohole array and Ag nanowire network after anti-rubbing test and anti-sonic test.